

High Voltage Hex Buffer / Driver Logic IC in bare die form

Rev 1.0 29/07/20

Description

The 5407 comprises x6 buffer/drivers with high voltage open-collector outputs. The device finds use as high-level circuit interface or for driving high-current loads and is also characterised to drive TTL inputs as buffer. The device has a 30V minimum breakdown voltage and 30mA maximum sink current.

Ordering Information

The following part suffixes apply:

- No suffix MIL-STD-883 /2010B Visual Inspection
- "H" MIL-STD-883 /2010B Visual Inspection+ MIL-PRF-38534 Class H LAT
- "K" MIL-STD-883 /2010A Visual Inspection (Space)
 + MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test.

For further information on LAT organism flows see below.

www.siliconsupplies.com\quality\bare-die-lot-qualification

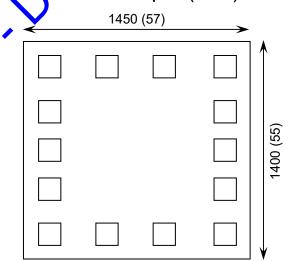
Supply Formats:

- Defaut Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape On request
- Unsawn Wafer On request
- Die Thickness <> 350µm(14 Mils) On request
- Assembled into Ceramic Package On request

Features:

- High Sink-Current Capability: 30mA
- High Voltage Open-Collector Drive
- Minimum breakdown voltage:
- Input Clamp Diodes minimize transmission-line effects
- TTL compatible inputs
- Direct drop-in replacement for obsolete components in long term programs

Die Dimensions in µm (mils)



Mechanical Specification

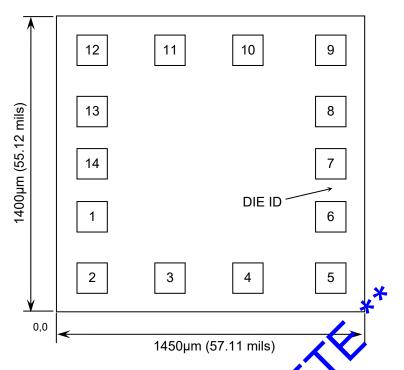
Die Size (Unsawn)	1450 x 1400 57 x 55	µm mils	
Minimum Bond Pad Size	140 x 140 5.5 x 5.5	μm mils	
Die Thickness	350 (±20) 13.78 (±0.79)		
Top Metal Composition	Al 1%Si 1.1μm		
Back Metal Composition	N/A – Bare Si		





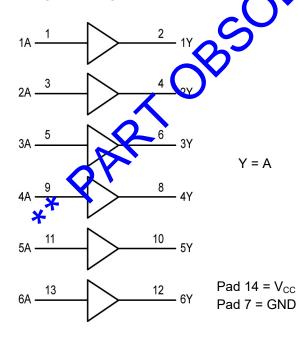
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Pad Layout and Functions



PAD	FUNCTION	COORDINATES (mi				
FAD	TONCTION	Х	Υ			
1	1A	0.099	0.380			
2	1Y	0.090	0.090			
3	2A	0.460	0.090			
4	2	0.830	0.090			
5	3A	1.220	0.090			
6	31	1.220	0.380			
70	GND	1.220	0.630			
2	4Y	1.220	0.880			
	4A	1.220	1.170			
10	5Y	0.830	1.170			
11	5A	0.460	1.170			
12	6Y	0.090	1.170			
13	6A	0.090	0.880			
14	V _{CC}	0.090	0.630			
CON	CONNECT CHIP BACK TO GND OR FLOAT					

Logic Diagram



Truth Table

INPUTS	OUTPUT				
A	Y				
Н	Z				
L	L				
H = High level (steady state)					
L = Low level (steady state)					
Z = High Impedance					





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Absolute Maximum Ratings¹

PARAMETER	SYMBOL	VALUE	UNIT
DC Supply Voltage	V _{CC}	7.0	V
DC Input Voltage	V _{IN}	5.5	/
DC Output Voltage	V _{OUT}	30	
Storage Temperature Range	T _{STG}	-65 to 150	°C

^{1.} Operation above the absolute maximum rating may cause device failure. Operation at the absolute maximum ratings, for extended periods, may reduce device reliability.

Recommended Operating Conditions

PARAMETER	SYMBOL	MIN	MAX	DNITS	
Supply Voltage	V _{CC}	4.5	5.5	V	
High-Level Input Voltage	V _{IH}	2		V	
Low-Level Input Voltage	V _{IL}	-	0.8	V	
High-Level Output Voltage	V _{OH}	-	30	V	
Low-Level Output Current	I _{OL}	X - /	30	mA	
Operating Temperature Range	T _J	* -55	+125	°C	

DC Electrical Characteristics² 7 = -35°C to 125°C unless otherwise specified

PARAMETER	SYMBOL	SYMBOL CONDITIONS	LIMITS			UNITS
FARAIVIETER	STIMBOL	MIN	TYP	MAX	UNITS	
Input Clamp Voltage	V _{IK}	V _{CC} = 4.5V, I _{IN} = -12mA	-	-	-1.5	V
High-Level Output Current	lon	$V_{CC} = 4.5V,$ $V_{IH} = 2V, V_{OH} = 30V$	-	-	0.25	mA
Low-Level Output	V _{OL}	$V_{CC} = 4.5V,$ $V_{IL} = 0.8V, I_{OL} = 16mA$	-	-	0.4	V
Voltage	VOL	$V_{CC} = 4.5V,$ $V_{IL} = 0.8V, I_{OL} = 30mA$	-	-	0.7	v
Inpu' C) rrent	I _{IN}	$V_{CC} = 5.5V, V_{IN} = 5.5V$	-	-	1	mA
High-Level Input Current	I _{IH}	V _{CC} = 5.5V, V _{IH} = 2.4V	-	-	0.04	mA
Low-Level Input Current	I _{IL}	$V_{CC} = 5.5V, V_{IL} = 0.4V$	-	-	-1.6	mA
Supply Current	I_{CC} $V_{CC} = 5.5V$, Output High $V_{CC} = 5.5V$, Output Low	V _{CC} = 5.5V ,Output High	-	-	41	mA
		-	-	30		





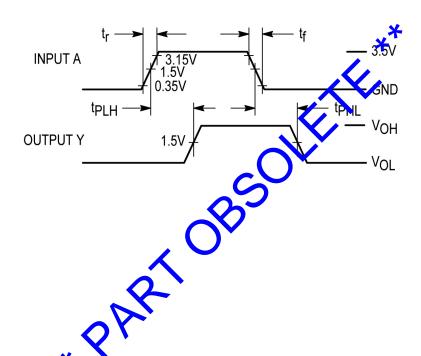
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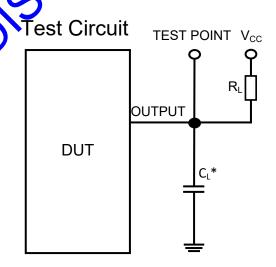
AC Electrical Characteristics²

PARAMETER	SYMBOL	CONDITIONS	LIMITS			LIMITS	
TARAMETER	01111202	CONDITIONS	MIN	TYP	MAX	ONITS	
Turn-Off Delay, Input to Output	t _{PLH}	$T_A = 25^{\circ}C$, $V_{CC} = 5V$, $R_L = 110\Omega$,	-	-	10		
Turn-On Delay, Input to Output	t _{PHL}	$C_L = 15pF,$ Input $t_r = t_f = 10ns$	-	-	13	ns	

2. Not production tested in die form, characterized by chip design

Switching Waveform





* Includes all probe and jig capacitance

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